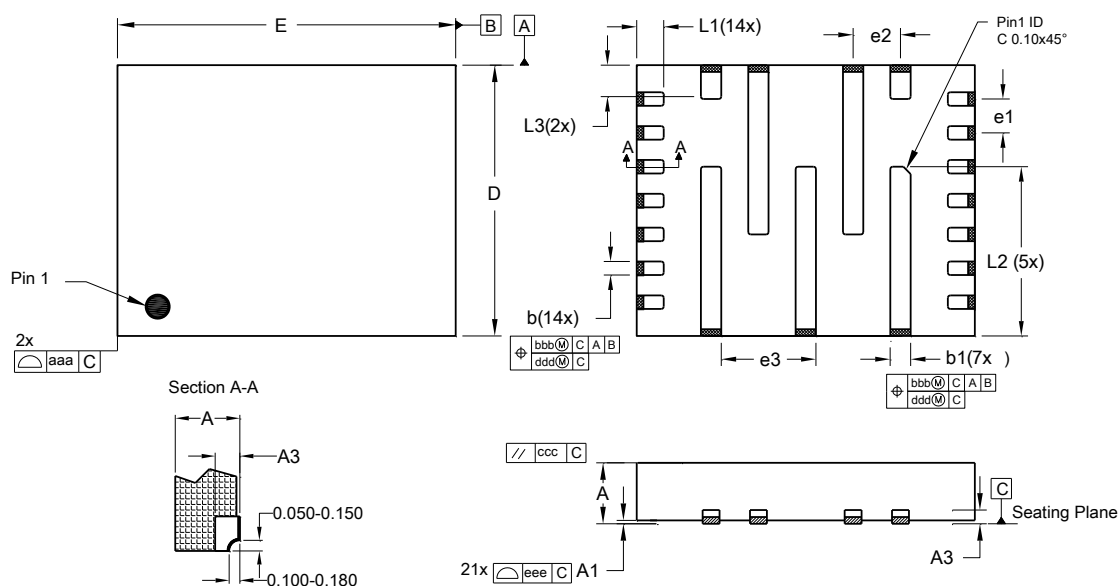


Package Outline Dimensions

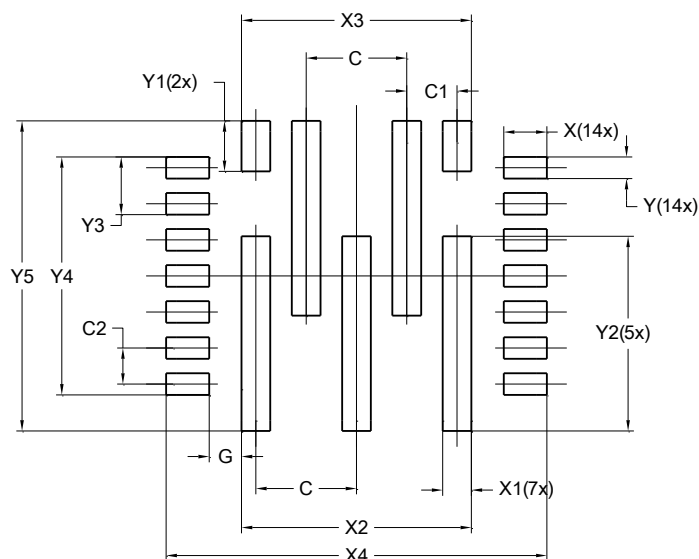
V-QFN4050-21/SWP (Type UM)



V-QFN4050-21/SWP (Type UM)			
Dim	Min	Max	Typ
A	0.800	0.900	0.850
A1	0.00	0.050	—
A3	0.203 REF		
b	0.150	0.250	0.200
b1	0.250	0.350	0.300
D	4.00 BSC		
E	5.00 BSC		
e1	0.500 BSC		
e2	0.700 BSC		
e3	1.400 BSC		
L1	0.350	0.450	0.400
L2	2.450	2.550	2.500
L3	0.450	0.550	0.500
aaa	0.050		
bbb	0.100		
ccc	0.050		
ddd	0.050		
eee	0.080		
All Dimensions in mm			

Suggested Pad Layout

V-QFN4050-21/SWP (Type UM)



Dimensions	Value (in mm)
C	1.400
C1	0.700
C2	0.500
G	0.450
X	0.600
X1	0.400
X2	3.200
X3	3.200
X4	5.300
Y	0.300
Y1	0.700
Y2	2.700
Y3	0.800
Y4	3.300
Y5	4.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.